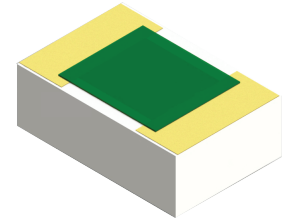


RS0805ZZ-XXXXWN-98 Features:

- Single-Sided (Flip-Chip) Terminal Configuration
- Solder, Epoxy or Wirebondable Terminals
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel (Film Side Down) and Waffle Pack Available (Standard is bulk)



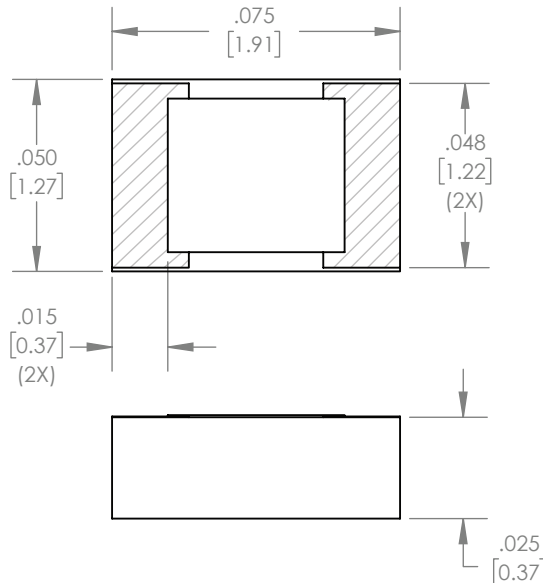
■ Actual Size

RS0805ZZ-XXXXWN-98 Parameters:

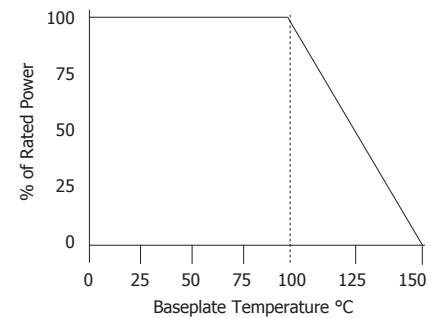
Resistance Range:	0.5Ω - 1MΩ
Rated Power:*	1W
Construction:	Thick Film on 0.025" BeO
Operating Temperature:	-55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RS0805ZZ-XXXXWN-98 Dimensions:



RS0805ZZ-XXXXWN-98 Power Derating Curve



Dimensions in inches [mm]
Tolerance is ± 0.005 [0.13]
unless otherwise stated

Ordering Information:

Example Part Number: RS0805CT-50R0JN-98

RS	0805	ZZ	-	XXXX	W	N	-	98	UU	
Prefix for Resistor w/ Single-Sided Terminals		Value Code		Tolerance		Normal Inspection Contact factory for additional options	Substrate		Packaging	
Size		50R0 - 50Ω	1002 - 10KΩ	F - 1%	98 - 0.025" BeO		Blank - Bulk		WP - Waffle Pack	
0805	1000 - 100Ω	1003 - 100KΩ	G - 2%	J - 5%			TRD - Tape & Reel			
Terminal Metallization		RoHS		Magnetic		Solder		Epoxy		Wirebond
AS -	Tin Lead over Platinum Palladium Gold	No		No		Yes		No		No
CB -	Tin Lead over Nickel over Silver	No		Yes		Yes		No		No
CC -	100% Matte Tin over Copper over Silver	Yes		No		Yes		No		No
CT -	100% Matte Tin over Nickel over Silver	Yes		Yes		Yes		No		No
JA -	Gold over Platinum Palladium Gold	Yes		No		No		Yes		Yes

Barry Industries reserves the right to change part number and/or process without notification.

RS0805ZZ-XXXXWN-98 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202 Method 210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +125 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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